

CALL FOR PAPERS

Abstracts Due: August 12, 2013 / Final Paper Due: March 3, 2014

SUBMIT YOUR ABSTRACT [HERE](#)

HOT Topics We're Looking For

Please feel free to submit an abstract on any subject, but keep in mind we're very interested in abstracts related to: LED Technology, Additive Manufacturing, Advanced Materials & Applications. See More Below!

RadTech International North America is pleased to invite you to submit an abstract for RadTech UV&EB Technology & Conference 2014, scheduled for May 12-14, 2014 at the Hyatt Regency O'Hare in Rosemont, IL. This is the foremost event for the UV/EB processing industry. As our industry has evolved, so has UV/EB technology grown to meet the new challenges. RADTECH's conference program will feature key areas of interest to the industry.

- Poster Session: A valuable opportunity for substantive discussion with the authors of shorter papers
- Variety of Specific Application Sessions
- Series of Technical Sessions & Best Technical Paper Award: \$1,000 cash award
- Best Student Paper Award: (2) \$500 Student Travel Grants

Those interested in presenting a technical conference paper no longer than 25 minutes in length with 5 minutes for Q&A at RadTech UV&EB Technology & Conference 2014 should complete and return the attached Abstract Submission Form prior to AUGUST 12, 2013. Your description should be sufficiently comprehensive to allow assessment of the scope and content of your paper by the Conference Committee. The Conference Committee will select papers and speakers will be notified whether or not they have been selected by SEPTEMBER 13, 2013. It is expected that a limited number of papers will be selected for TECHNICAL CONFERENCE and POSTER SESSION! Due to the limited space we have available, please submit your paper by the deadline to ensure consideration for presentation or inclusion in the poster sessions. The Presentations and Poster Sessions have equal status and are two different venues for presenting new science and technology.

Speakers will receive an instruction manual providing details to help prepare written and oral presentation as well as audiovisual aids. Speakers will be asked to use terminology consistent with the RADTECH UV Measurement Glossary when preparing papers. A copy of the Glossary may be found online at: http://www.radtech.org/index.php?option=com_content&view=article&id=69&Itemid=78. Speaker registration forms will be included in your instruction manual. Speakers may register at 50% off the member or non-member registration category.

The deadline for submitting your final paper for publication is MARCH 3, 2014. Speakers agree to submit a written paper to be published in the conference proceedings, as well as develop a Power Point presentation if presenting within a session, in order to be considered for the conference program.

Please consider the following suggested topics:

HOT – LED TECHNOLOGY

- Formulations
- Equipment Innovations
- Exciting Applications
- Economics / Case Studies

HOT – ADDITIVE MANUFACTURING

- Formulations
- Equipment Innovations
- Exciting Applications

HOT – ADVANCED MATERIALS

- Graphene
- Superhydrophobic Coatings
- Metamaterials
- Anti-Corrosion & Weathering
- Bio-Based / Renewable
- Enabling
- Antimicrobial
- Smart & Self Healing
- Fire Retardant
- Low Migration
- Nanomaterials
- Conductive Polymers
- Formaldehyde Free

HOT – APPLICATIONS AREAS

- Printed Electronics
- Photovoltaics
- Mobile Finishing / Refinishing
- Sensors
- Display Technology
- PC-MEMS
- Wind Turbines

ADVANCES IN CHEMISTRIES

- Monomers/Diluents
- Oligomers/Resins
- Photoinitiators
- Cationic Curing
- Additives & Pigments
- Hybrid Systems
- Novel Chemistry
- Waterborne
- 100% Solids Formulations
- New Techniques

FORMULATION PARAMETERS

- Modeling
- Cure Kinetics
- Lab Efficiency
- Advanced Formulations

ADVANCES IN EQUIPMENT

- UV and EB Curing Advancements
- Substrate Treatment
- 3-Dimensional
- Mobile Finishing & Refinishing

TESTING & MEASUREMENT

- Process Control
- Physical/Chemical Properties
- UV Measurements
- Analytical Methods
- VOC Calculations
- Quality Assurance
- Degree of Cure
- Adhesion Issues